

L Number	Hits	Search Text	DB	Time stamp
1	0	((test or probe) near Pad) and aluminum and copper").PN.	USPAT; US-PPGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/01 20:01
2	291	((test or probe) near Pad) and aluminum and copper	USPAT; US-PPGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/01 20:01
3	199	((test or probe) near Pad) and aluminum and copper) and wire	USPAT; US-PPGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/01 20:02
4	51	((test or probe) near Pad) and aluminum and copper) and ((wire adj bond) or wirebond)	USPAT; US-PPGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/01 20:18
5	274	(test with ((wire adj bond) or wirebond))	USPAT; US-PPGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/01 20:06
6	196	((test with ((wire adj bond) or wirebond))) and (chip or die)	USPAT; US-PPGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/01 20:07
7	151	((test with ((wire adj bond) or wirebond))) and (chip or die)) and pad	USPAT; US-PPGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/01 20:18
8	33	257/48.ccls. and ((wire adj bond) or wirebond)	USPAT; US-PPGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/01 20:19
9	28	(damage near active) and ((wire adj bond) or wirebond)	USPAT; US-PPGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/01 20:24
10	36	(damage near pad) and ((wire adj bond) or wirebond)	USPAT; US-PPGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/01 20:25
11	1	(prevent near active) and ((wire adj bond) or wirebond)	USPAT; US-PPGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/01 20:25
12	188	257/784.ccls. and ((wire adj bond) or wirebond)	USPAT; US-PPGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/01 20:27
13	101	257/784.ccls. and offset	USPAT; US-PPGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/01 20:27
14	811	257/784.ccls. and pad	USPAT; US-PPGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/01 20:27

15	680	(257/784.cccls. and pad) and wire	USPAT; US-PPGUB; EPO; JPO; DERWENT; IBM TDB	2003/06/01 20:27
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